

# Radiation TID and Traps Effects in Al<sub>2</sub>O<sub>3</sub>/Ga<sub>2</sub>O<sub>3</sub> MIS Capacitors

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## Motivation

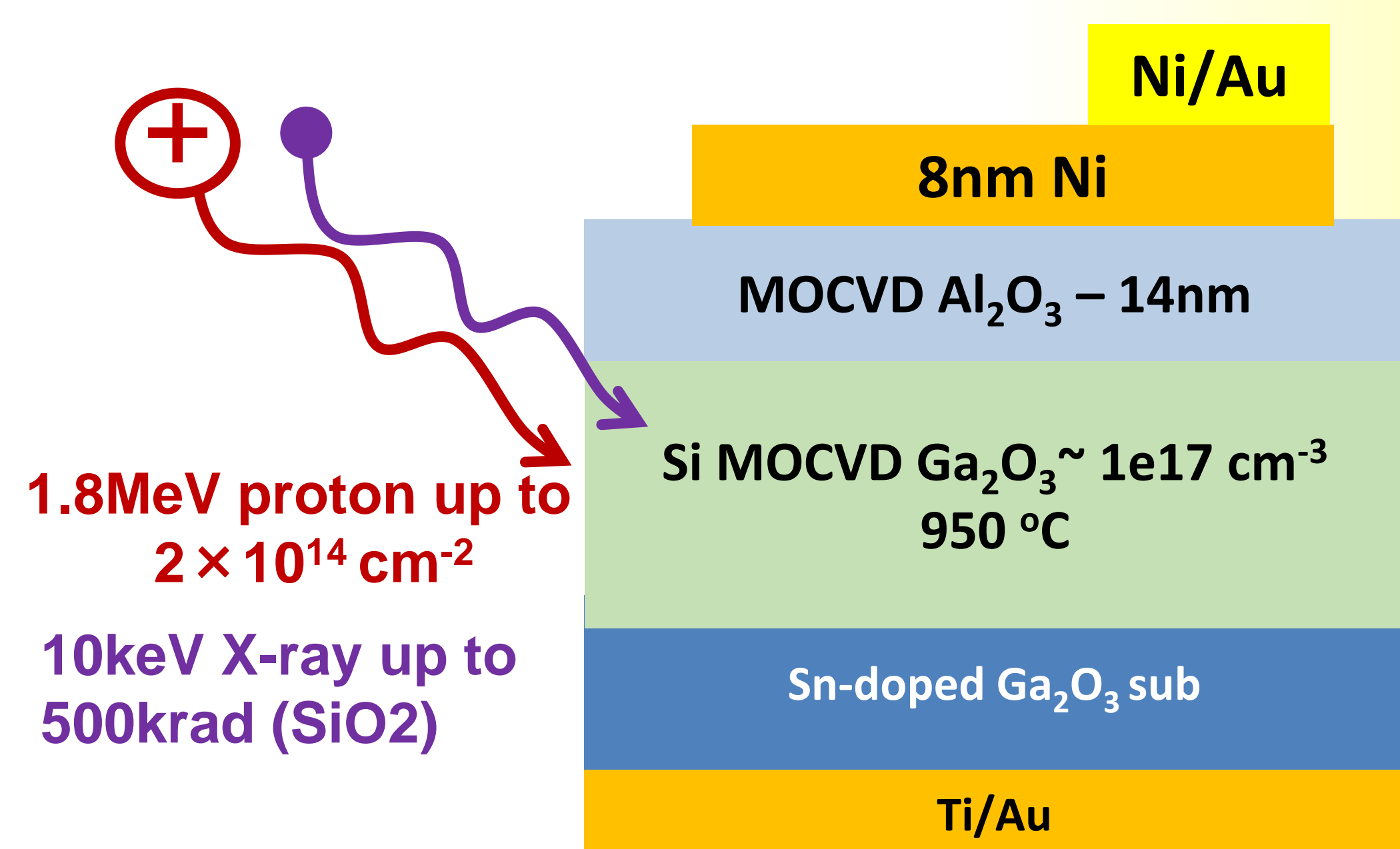
$\beta$ -Ga<sub>2</sub>O<sub>3</sub> is a 4.8 eV ultra wide bandgap (UWBG) semiconductor known for its **large breakdown field**<sup>[1]</sup> and **radiation resistance**<sup>[2]</sup>. To date, little work has been done on the impact of total ionizing radiation (TID) in  $\beta$ -Ga<sub>2</sub>O<sub>3</sub> devices. Understanding TID effects along with prior work on displacement damage (DD) is needed to advance tech development that exploits the radiation hardness of  $\beta$ -Ga<sub>2</sub>O<sub>3</sub> for applications in radiation-rich environments and as remote radiation detectors.

**Objective:** This work investigates DD and TID effects in Al<sub>2</sub>O<sub>3</sub>/Ga<sub>2</sub>O<sub>3</sub> MIS capacitors by **comparing proton and x-ray irradiation** effects on electrical properties using capacitance-voltage (C-V) analyses.

## Key Experimental Method

### Approach:

- Apply 1.8 MeV proton up to  $2 \times 10^{14}$  cm<sup>-2</sup> fluence and 10keV X-ray up to 500krad (SiO<sub>2</sub>) with in-situ voltage biasing during each radiation dose step.
- Radiation effects on devices are characterized through C-V characteristics.
- The effects of TID, DD and interface trapping can be quantified by comparing C-V threshold voltage shifts,  $\Delta V_{FB}$ .

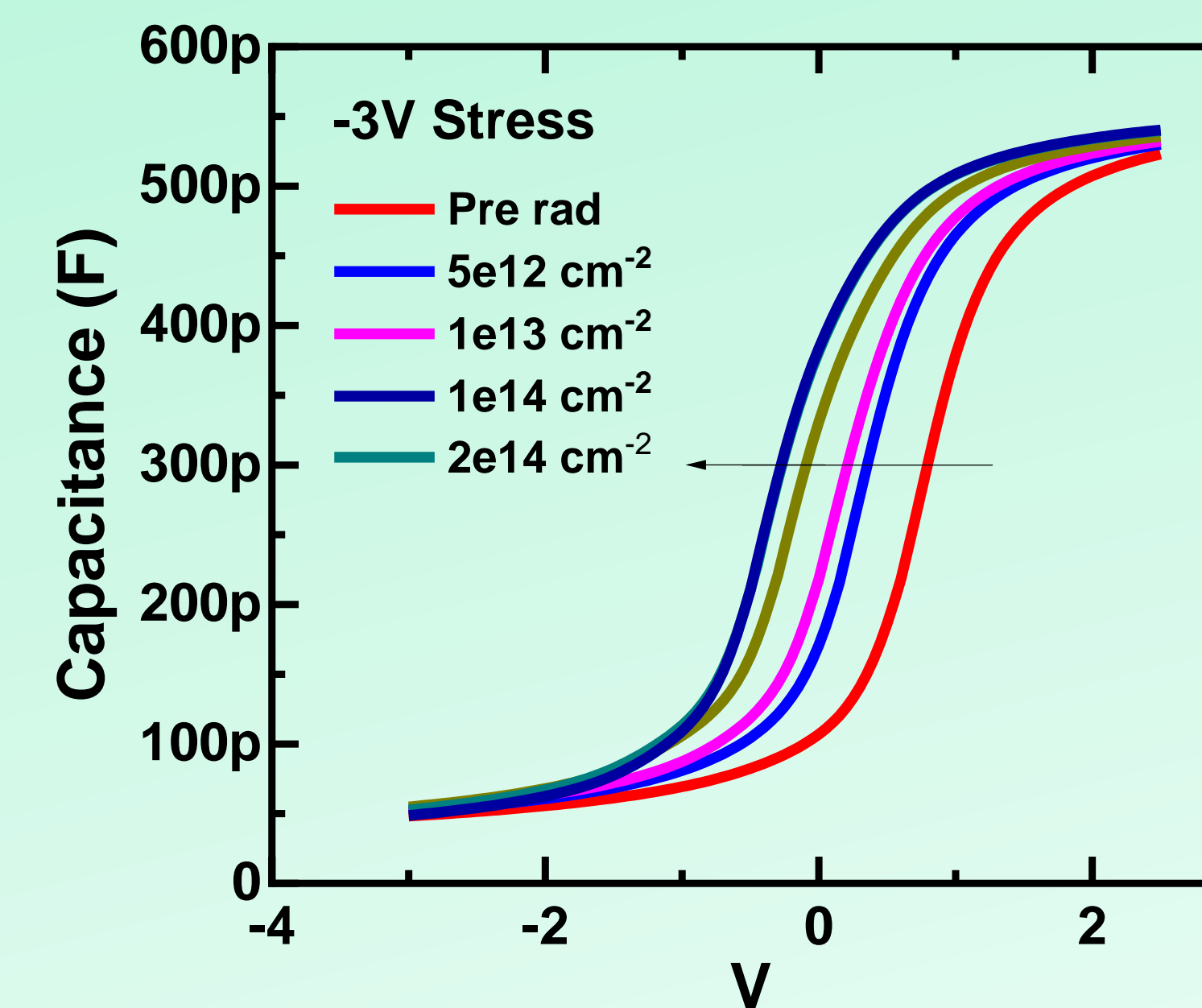


MIS device structure used for radiation response testing

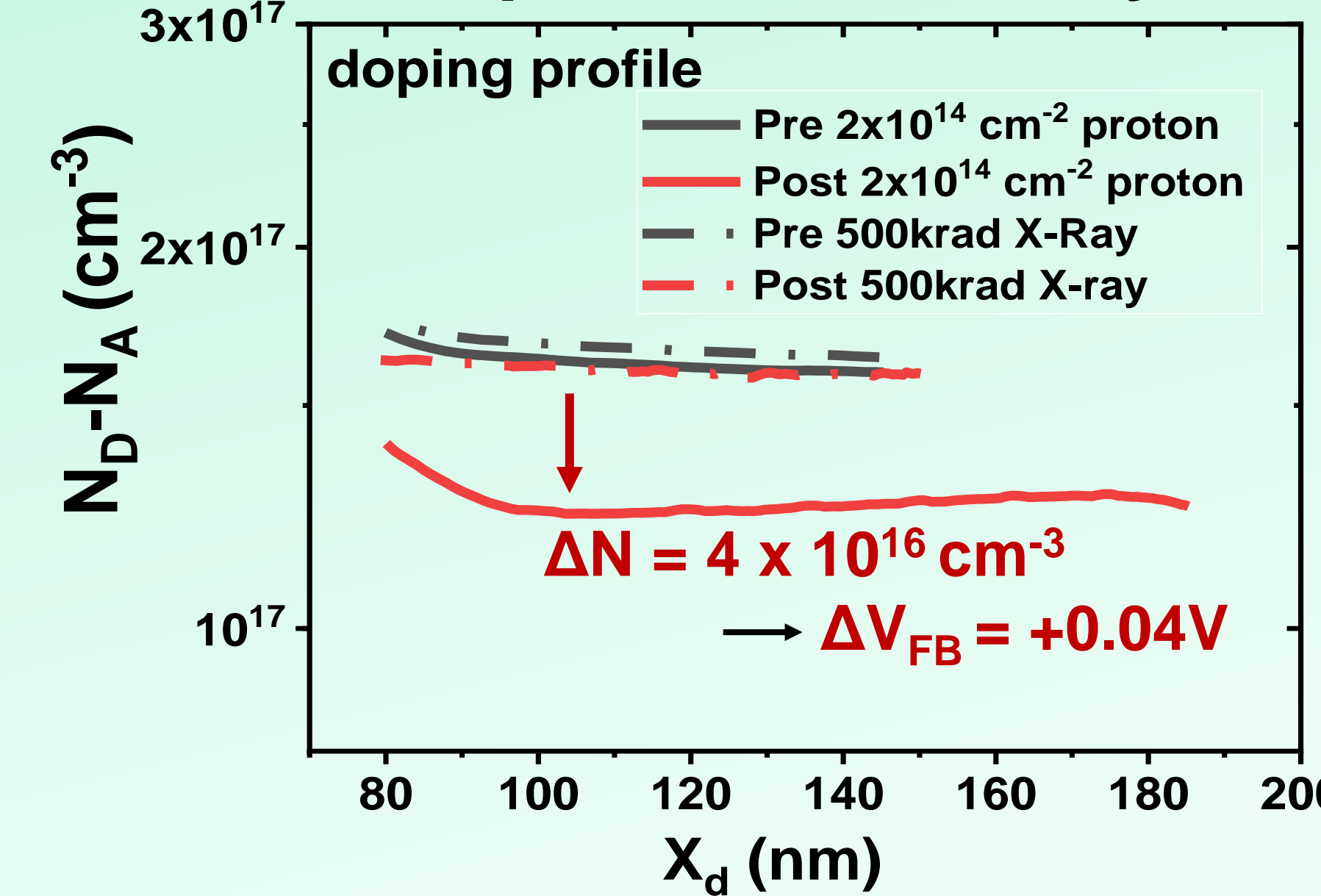
[1] Higashiwaki *et al.*, Appl. Phys. Lett. 100, 013504 (2012)  
[2] E. Wendler *et al.*, 11th Intl. Conf. Interact. of Rad. with Sol., 93, (2015)

## Effects of DD & TID on Al<sub>2</sub>O<sub>3</sub>/Ga<sub>2</sub>O<sub>3</sub> MIS capacitors

### C-V: proton irradiated



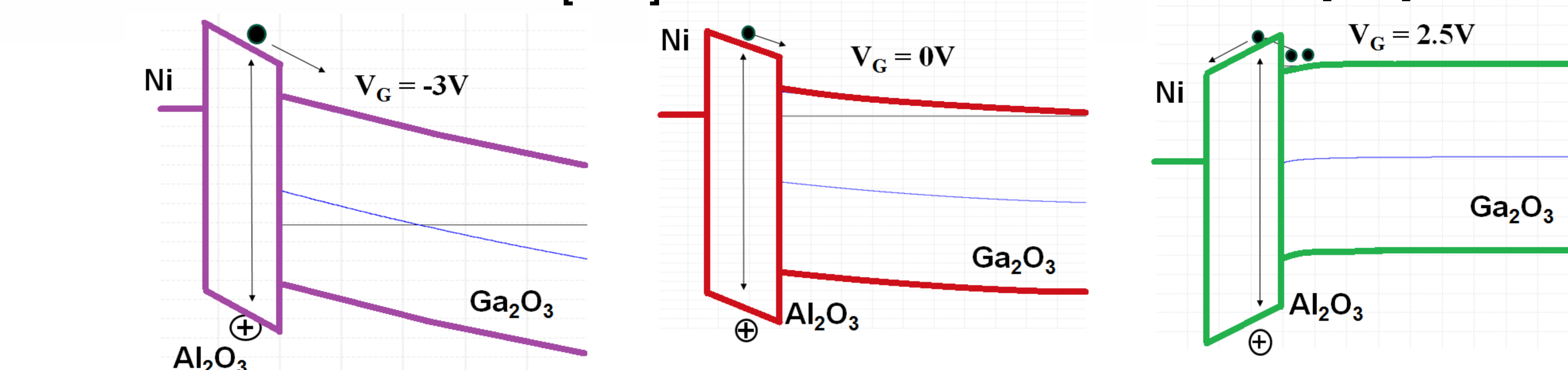
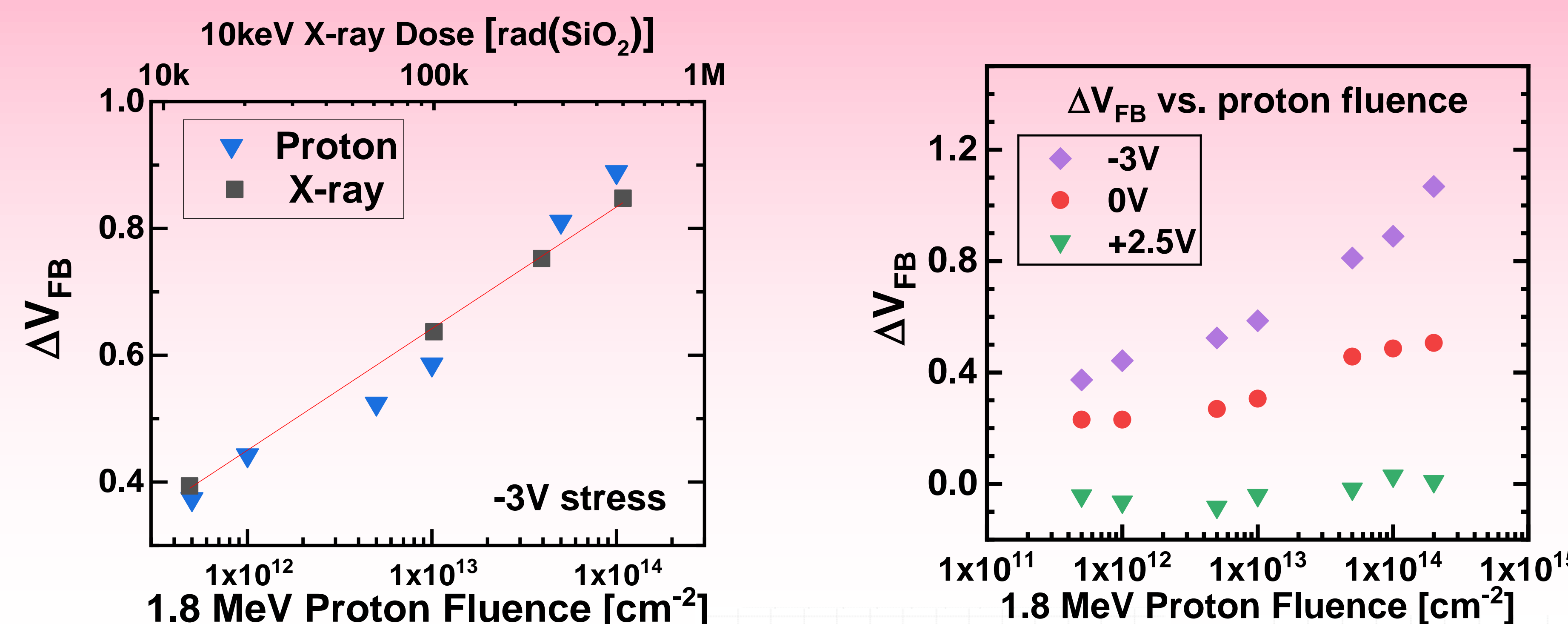
### Carrier removal comparison: protons and X-rays



Protons can cause both TID & DD effects

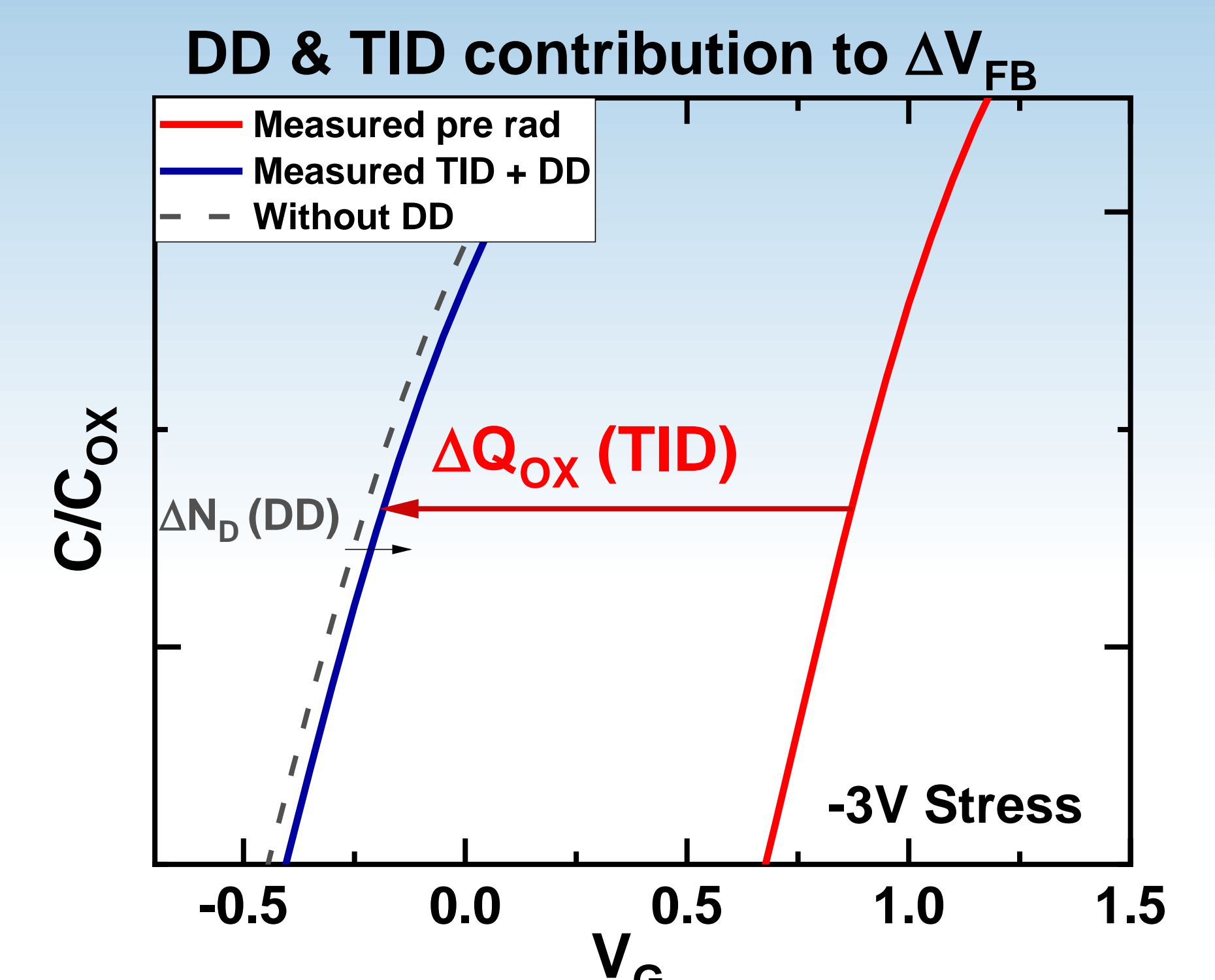
- large  $\Delta V_{FB}$  seen in C-V
  - Monotonic negative shift** implies increased positive charge inside dielectric.
  - Carrier removal from bulk material due to DD-induced traps as expected, but only accounts for **+0.04** of total  $\Delta V_{FB}$ .
- X-ray is shown to cause mostly TID, as:
- Minimal carrier removal** (DD effects) observed, as expected.

### Comparison of proton and x-ray irradiation on $\Delta V_{FB}$ with in-situ bias



- TID effect **increases** with field strength. As higher field strength prevents recombination of ionized EHPs.
- Negligible  $\Delta V_{FB}$  at forward bias indicates putting devices into accumulation helps mitigate TID damage.
- Equivalent amount of  $\Delta V_{FB}$  caused by proton can be obtained entirely from X-ray within chosen dose range.
- TID caused  $\Delta V_{FB}$  were an order of magnitude **higher** than DD.

## Conclusions & future work



- Impact of **displacement damage** and **TID** on Ga<sub>2</sub>O<sub>3</sub> MIS devices were investigated using **proton** and **X-ray** irradiation.
- TID effects from proton irradiation were isolated and identified by comparing with X-ray irradiation results.
- TID effects from protons and x-rays **almost identical**.
- DD due to proton irradiation accounts for **< 10%** of measured  $\Delta V_{FB}$

In collaboration with the Sandia National Lab IBL team.

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